

Average Weight: 5.7254g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.21084	3.683%
	Silicon	7440-21-3	100		0.21084	
Solder Bump					0.01131	0.197%
	Tin	7440-31-5	63		0.00712	
	Lead	7439-92-1	37		0.00418	
Underfill					0.03300	0.576%
	Silica	60676-86-0	70		0.02310	
	Epoxy Resin A	9003-36-5	20		0.00660	
	Epoxy Resin B	25068-38-6	3		0.00099	
	Hardener	19900-65-3	7		0.00231	
Heat Spreader					2.90000	50.652%
	Copper (Cu)	7440-50-8	99.60		2.88840	
	Nickel (Ni)	7440-02-0	0.40		0.01160	
Heat Spreader Adhesive					0.03000	0.524%
	Organopolysiloxane mixture	N/A	100		0.03000	
Substrate					1.07000	18.689%
	Copper	7440-50-8	46.91	Metal Layer	0.50194	
	Nickel	7440-02-0	0.52	Metal Layer	0.00556	
	Gold	7440-57-5	0.12	Metal Layer	0.00128	
	Halogen fire retardant	N/A	5.25		0.05618	
	Glass Fiber	N/A	10.5		0.11235	
	BT (core)	N/A	28		0.29960	
	Solder Mask (EP)	N/A	8.7		0.09309	
Solder Balls					1.47024	25.679%
	Tin	7440-31-5	63		0.92625	
	Lead	7439-92-1	37		0.54399	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
10/05/06	1.0	Initial Xilinx release.
07/06/09	1.1	Revised heat spreader composition. Revised average weight to correct calculation error.

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